

PCN# 20170327000 Qualification of MIHO8 as an additional Wafer Fab Site option for select devices Change Notification / Sample Request

Date:March 29, 2017To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

PCN Team SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM43600PWPR	null
LM43602PWP	null
LM46002PWPT	null
LM43601PWPR	null
LM43601PWPT	null
LM43603PWPT	null
LM46002PWPR	null
LM43602PWPR	null

Technical details of this Product Change follow on the next page(s).

Title: Qualification of MIHO8 as an additional Wafer Fab Site option for select devices Technology Customer Contact: PCN Manager Dept: Quality Service Proposed 1 st Ship Date: Jun 29, 2017 Estimated Sample Availability: Date provided request. Change Type: Assembly Site Assembly Process Assembly Material Design Electrical Specification Mechanical Specification Test Site Packing/Shipping/Labeling Test Process	s at sample als ification cess ss	
Title: Technology Customer Contact: PCN Manager Dept: Quality Service Proposed 1 st Ship Date: Jun 29, 2017 Estimated Sample Availability: Date provided request. Change Type: Assembly Site Assembly Process Assembly Material Design Electrical Specification Mechanical Specification Test Site Packing/Shipping/Labeling Test Process	s at sample als ification cess ss	
Proposed 1 st Ship Date: Jun 29, 2017 Estimated Sample Availability: Date provided request. Change Type: Assembly Site Assembly Process Assembly Mater Design Electrical Specification Mechanical Specification Test Site Packing/Shipping/Labeling Test Process	at sample als ification cess ss	
Proposed 1** Ship Date: Jun 29, 2017 Availability: request. Change Type:	als ification cess ss	
Assembly Site Assembly Process Assembly Mater Design Electrical Specification Mechanical Specification Test Site Packing/Shipping/Labeling Test Process	ification cess ss	
Design Electrical Specification Mechanical Specification Test Site Packing/Shipping/Labeling Test Process	ification cess ss	
Test Site Packing/Shipping/Labeling Test Process	cess ss	
	SS	
	SS	
Wafer Bump Site Wafer Bump Material Wafer Bump Pro		
Wafer Fab Site Wafer Fab Materials Wafer Fab Proce	as an	
Part number change	as an	
PCN Details Description of Change:	as an	
Texas Instruments is pleased to announce the qualification of its MIHO8 fabrication facility	us un	
additional Wafer Fab source for the selected devices listed in "Product Affected" section.		
Current Sites Additional Sites	Sites	
CurrentProcessWaferAdditionalProcessWaferFab SiteDiameterFab SiteDiameter		
DP1DM5 LBC8 200mm MIH08 LBC8 200mm		
Qual details are provided in the Qual Data Section.		
Reason for Change:		
Continuity of Supply		
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negati	/e):	
None		
Changes to product identification resulting from this PCN:		
Current		
Chip Site Chip Site Origin (20L) Chip Site Country Code (21L) Chip Site City	,	
DP1DM5 DM5 USA Dallas		
New Fab Site		
Chip Site Chip Site Origin (20L) Chip Site Country Code (21L) Chip Site City		
MIHO8 MH8 JPN Ibaraki		
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 (not actual product label) (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) 2DC SO: SHE (2DL) CSO: SHE (2D		

Product Affected:					
LM43600PWP	LM43602PWP	LM43603PWPT	LM46001PWPR		
LM43600PWPR	LM43602PWPR	LM46000PWP	LM46001PWPT		
LM43600PWPT	LM43602PWPT	LM46000PWPR	LM46002PWP		
LM43601PWP	LM43603PWP	LM46000PWPT	LM46002PWPR		
LM43601PWPR	LM43603PWPR	LM46001PWP	LM46002PWPT		
LM43601PWPT					

Qualification Report LM46002PWP Approve Date 24-Feb-2017

Product Attributes

Attributes	Qual Device: LM46002PWPR
Assembly Site	TI – Taiwan
Package Family	HTSSOP
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	TI – Japan
Wafer Fab Process	Power BiCMOS LBC8

- Qual Device LM46002PWPR is qualified at LEVEL3-260C

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LM46002PWP
PC	Preconditioning Level 3	260C	3/693/0
HTOL	Life Test, 150C	300 hours	3/231/0
ELFR	Early Life Failure Rate, 150C	24 hours	3/2400/0
AC	Autoclave 121C	96 hours	3/231/0
тс	Temperature Cycle, -65/150C	500 cycles	3/230/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 hours	3/231/0
HTSL	High Temperature Storage Life, 150C	1000 hours	1/77/0
HBM	ESD – HBM	2500 V	1/3/0
CDM	ESD - CDM	1000 V	1/3/0
LU	Latch-up	25C	1/6/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com